Timothy K. Paine

tim.paine.nyc timkpaine timothy.k.paine@gmail.com NYC

Experience

Present | Feb 2022

Point72

Central Research Team - Cubist Systematic Strategies

- Building out centralized technology, research, and trading teams
- From infrastructure to UI across all asset classes and teams

Present | May 2015

Columbia University

Associate in Computer Science (Faculty)

- Courses include languages, algorithms and data structures, systems, and software engineering

Dec 2021 | Nov 2020

IEX

Head of Software Engineering - Cloud

- Established engineering best practices on a rapid growth team
- Overhauled all aspects of the software development lifecycle
- Led feature developments for existing and new product verticals

Nov 2020 | Mar 2016

J.P. Morgan

Vice President - Athena Core

- Led development of a cloud research environment for ~1500 developers, quants, and traders
- Developed high performance applications for real time post trade analytics
- Overhauled core systems, components, and processes for development and integrations

Jan 2016 | Jul 2015

MayStreet

Software Engineer

- Developed low latency market data and order entry systems for equity and options exchanges

Education

Columbia University

B.A. Computer Science/Mathematics
B.S. Computer Engineering Magna Cum Laude
M.S. Computer Engineering
All degrees completed concurrently

Projects

Helped established OSS organizations at J.P. Morgan and Point72, contributor/maintainer of many large scale open source projects.

Media

Production Notebooks | JupyterCon 2020 | tim.paine.nyc/talks/jupytercon
Beyond Spreadsheets | NYC Data Council 2020 | youtu.be/PYTVU4A_3Kc
JPMorgan's requirement for new staff: coding lessons | Financial Times
JPMorgan's Python training guide for analytics and traders | efinancialcareers

Publications

Q100: The Architecture and Design of a Database Processing Unit
L.Wu, A. Lottarini, T. Paine, M. Kim, K.Ross

ASPLOS 2014: Nineteenth International Conference on Architecture Support for Programming Languages and Operating Systems. ***IEEE Micro Top Pick****.*